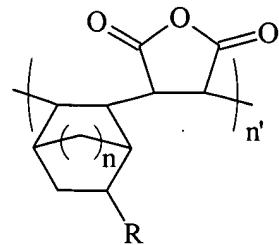


AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

Claims 1-18 (Canceled)

19. (Currently Amended) A method of fabricating a device, comprising:
fabricating an integrated circuit chip, the integrated circuit chip including
a plurality of electrical bond pads;
fabricating a substrate;
positioning the integrated circuit chip relative to the substrate;
providing electrical connection between the integrated circuit chip and the
substrate during a reflow operation;
providing an underfill composition between the integrated circuit chip and the
substrate, the underfill composition including
a resin; and
a curing agent selected from the group consisting of low molecular weight
maleic anhydride polymers, low molecular weight maleic anhydride
oligomers, and a mixture thereof, wherein if the maleic anhydride polymer
is a copolymer comprising norbornene, then the copolymer has the
following structural formula:



where n is 1 to 3, n' is 5 to 50, and R is selected from the group consisting of ethers, lactones, anhydrides, alcohols, nitriles, epoxy, carboxylic acids and mixtures thereof, and wherein the molecular weight of the curing agent is greater than about 1000 g/mole.

20. (Original) The method according to claim 19 wherein the underfill composition is provided simultaneously during reflow.

21. (Original) The method according to claim 19 wherein the underfill composition is provided after reflow.

22. (Original) The method according to claim 19 wherein the underfill composition is cured.

23. (Previously Presented) The method according to claim 22 wherein the curing occurs within a temperature range of from about 130° C to about 170° C.

24. (Previously Presented) The method according to claim 22 wherein the curing occurs within about 5 minutes to about 4 hours.

25. (Previously Presented) The method according to claim 19 wherein the maleic anhydride polymer is a copolymer selected from the group consisting of cyclohexane/maleic anhydrides, styrene/maleic anhydrides, and mixtures thereof.